


## APPLICATION DATA SHEET

Electronic Version v14

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<b>Title of Invention</b>	[METHOD OF ENHANCING THE ADHESION BETWEEN PHOTORESIST LAYER AND SUBSTRATE AND BUMPING PROCESS]		
Application Type : regular, utility Attorney Docket Number : 11577-US-PA			
Correspondence address: Customer Number: 31561 			
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<b>Inventor Information:</b>  <u>Inventor 1:</u> <b>Applicant Authority Type:</b> Inventor <b>Citizenship:</b> TW <b>Name prefix:</b> Mr. <b>Given Name:</b> Min-Lung <b>Family Name:</b> Huang <b>Residence:</b> <b>City of Residence:</b> Kaohsiung <b>Country of Residence:</b> TW <b>Address-1 of Mailing Address:</b> 10F., No. 8, Alley 2, Lane 33, Ting-yung St., <b>Address-2 of Mailing Address:</b> San-min Chu <b>City of Mailing Address:</b> Kaohsiung <b>State of Mailing Address:</b> <b>Postal Code of Mailing Address:</b> <b>Country of Mailing Address:</b> TW <b>Phone:</b> <b>Fax:</b> <b>E-mail:</b>			
<b>Attorney Information:</b> practitioner(s) at Customer Number:			

31561



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